### **Field Effect Transistor**

# Silicon N Channel MOS Type (t-MOS IV)

# High Speed, High Current Switching Applications

#### **Features**

- Low Drain-Source ON Resistance
- $R_{DS(ON)} = 0.24\Omega$  (Typ.) High Forward Transfer Admittance
- $|Y_{fs}|$  = 15S (Typ.)
- Low Leakage Current
  - $-I_{DSS} = -100\mu A \text{ (Max.) (V}_{DS} = 500\text{V)}$
- Enhancement-Mode
  - $V_{th} = 2.0 \sim 4.0 V (V_{DS} = -10 V, I_D = 1 mA)$

#### Absolute Maximum Ratings (Ta = 25C)

CHARACTERISTIC		SYMBOL	RATING	UNIT	
Drain-Source Voltage		V <sub>DSS</sub>	500	٧	
Drain-Gate Voltage (R <sub>S</sub> = 20kΩ)  Gate-Source Voltage		V <sub>DGR</sub> Vass	500	٧	
			±30	٧	
Drain Current	DC	Ь	20	Α	
	Pulse	1 <sub>OP</sub>	80		
Drain Power Dissipation (Tc = 25°C)		P <sub>D</sub>	150	W	
Channel Temperature		Th	150	°C	
Storage Temperature Range		- Itg	-55 - 150	°C	

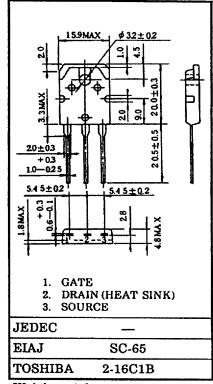
#### **Thermal Characteristics**

CHARACTERISTIC	SYMBOL	MAX.	UNIT
Thermal Resistance, Channel to Case	ff(ch-c)	0.833	°C/W
Thermal Resistance, Channel to Ambient	fil(ch-a)	50	°C/W

This transister is an electrostatic sensitive device. Please handle with caution.

### **Industrial Applications**

Unit in mm



Weight: 4.6g

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## Electrical Characteristics (Ta = 25C)

CHARAC	CTERISTIC	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Gate Leakage Cur	Leakage Current $k_{SS}$ $V_{GS} = \pm 25V$ , $V_{DS} = 0V$				±10	nA	
Gate-Source Breakdown Voltage		V <sub>(BR) DSS</sub>	$I_{G} = \pm 100V, V_{DS} = 0V$	±30	-	- 1	μA
Drain Cut-off Cur	rent	loss	1 <sub>DSS</sub> V <sub>DS</sub> = 500V, V <sub>GS</sub> = 0V	_	-	100	μΑ
Drain-Source Bre	akdown Voltage	(BR) DSS	I <sub>D</sub> = 10mA, V <sub>GS</sub> = 0V	500	_	-	٧
Gate Threshold Voltage		<b>V</b> h	$V_{DS} = 10V$ , $b = -1mA$	2.0	-	4.0	٧
Drain-Source ON	Resistance	Pos (ON)	V <sub>GS</sub> = 10V, I <sub>D</sub> = 10A	-	0.24	0.30	Ω
Forward Transfer	Admittance	Y <sub>ts</sub> I	V <sub>DS</sub> = 10V, I <sub>DS</sub> = 10A	10	15	-	S
Input Capacitance Reverse Transfer Capacitance Output Capacitance		Gss	V <sub>DS</sub> = 10V, V <sub>GS</sub> = 0V, f = 1MHz	-	3000	4800	DF
		Çss			220	270	
		Coss			830	1200	μı
	Rise Time	tr		_	25	50	
Switching Time	Turn-on Time	bn	ID-IOA	-	60	120	ns
•	Fall Time	1	Ves er 10 a	_	55	110	113
Turn-	Turn-off Time	рщ	Ves of 100 Vest 100 Vest 100 Vest 100 Vest 100 Vest 200 V	_	280	560	
Total Gate Charge Q <sub>g</sub> (Gate-Source Plus Gate-Drain)  Gate-Source Charge Q <sub>g</sub>		Qg	V <sub>DD</sub> = 400V, V <sub>GS</sub> = -10V,	_	65	130	nC
		Q <sub>s</sub>			40	_	
Gate-Drain ("Mill	er") Charge	Q <sub>d</sub>		_	25	-	

## Source-Drain Diode Ratings and Characteristics (Ta = 25C)

CHARACTERISTICS	SYMBOL	TEST CONDITION	MIN.	TYP.	MAX.	UNIT
Continuous Drain Reverse Current	da	-		_	20	Α
Pulse Drain Reverse Current	DRP	-	- 1		80	Α
Diode Forward Voltage	Yosf	I <sub>DR</sub> = 20A, V <sub>GS</sub> = 0V		-1.0	-1.7	٧
Reverse Recovery Time	*	I <sub>DR</sub> = 20A, V <sub>GS</sub> = 0V		450	-	ns
Reverse Recovered Charge	Q,	dl <sub>DR</sub> / <sub>dt</sub> = 100A/µs	-	6.8		μC

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